



DOCUMENT CHANGE REQUEST

DCR number	1353	Changes required for:	General	Originator:	Steve Thacker
Date:	2020/10/02	Date sent:	2020/07/23	Organisation:	ESCC Executive Secretariat
Status:	IMPLEMENTED				

Title: Diodes Microwave Silicon PIN, based on BXY42-MESA

Number: 5513/017 Issue: 6

Other documents affected:

Page:

as below

Paragraph:

as below

Original wording:

as per issue 6

Proposed wording:

Per request from Manufacturer, Infineon, to add new variants, the following changes apply (see attached markup specification 5513/017 Draft 7 with changes highlighted yellow):

Para 1.4.2
Add new Variants 03 & 04 (based on existing Variants 01 & 02 respectively, but from a different size wafer).
Table column added to clarify the differences between Variants.

Para 1.5, 2.5.1, 2.7
Add new variants 03 & 04 to the requirements (see attached for details)

Para. 1.6
Change Minimum Critical Path Failure Voltage to be 250V (was 100V)

Appendix A
Add deviation on Component type variants to explain the differences between existing and new variants (i.e different wafer sizes)

Justification:

as above

Attachments:

5513017_draft_7c_in_review.docx, 5513017_draft_7e_in_review.docx

Modifications:

The following additional changes, as detailed in the revised attachment/mark up (highlighted green) 5513/017 Draft7E, shall apply as discussed and agreed with Infineon: new variant added to this spec is now only 03

Approval signature:

A handwritten signature in black ink, appearing to read "Augustin Reu".

Date signed:

2020-10-02